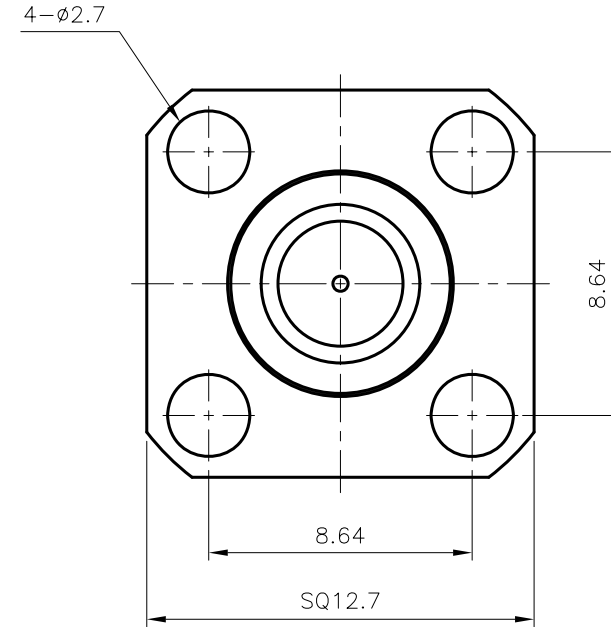
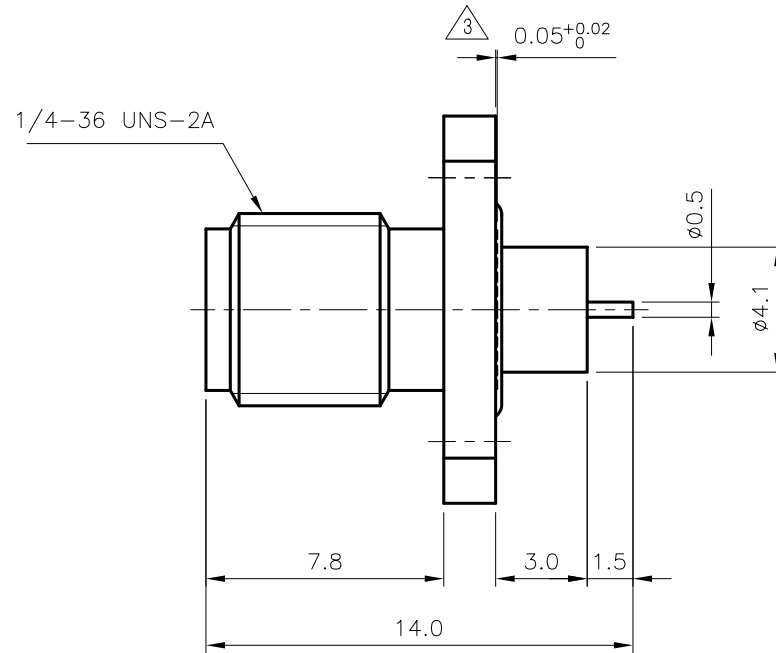


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	E.H.KIM	I.C.KIM	2014.10.30.
1	[설변 No.201502-0003] 업체요청 (가스켓 깊이변경)	S.M.LEE	I.C.KIM	2015.02.07.
2	[설변 No.201905-0005] 고객사요청 (핀 도금두께 변경 및 가스켓 사이즈 변경)	S.Y.EUN	I.C.KIM	2019.05.31.
3	고객사 요청 BODY 길이 수정	I.C.KIM		2021.09.03.



2	4	INSULATOR	1	TEFLON		DIN00190-N/1
	3	GASKET	1	SILICONE RUB		DGK00237-N/1 DGK00020-N/1
	2	CONTACT	1	BeCu	Gold (1.27μm) Gold Plate	DCT03272-5/1
	1	BODY	1	SUS	Passivate	DBD03763-5/2 DBD03763-5/1
3 2	NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE
Decimal ±0.2	DATE 2021. 09. 03.			KJ  COMTECH KJ COMTECH CO.,LTD. RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017		
Angle ±1°	APPROVED BY					
	CHECKED BY			TITLE		
	DRAWN BY		I.C.KIM	SMA50 SOLDER END JS-4H		
	SCALE 4/1	UNIT mm		A4	DWG NO. REVISION 3	CN03328-7/2 SHEET 1 of 1